DSA613

Three-Output Low Power MEMS Clock Generator for Automotive

Features

- Automotive AEC-Q100 Qualified
- MEMS-Based Clock Generator Eliminates the Need for External Crystal or Reference Clock
- Three LVCMOS Output Clocks: 2 kHz to 100 MHz
- Low Power Consumption: 5.2 mA (All Outputs Active)
- Wide Supply Voltage Range: 1.71V to 3.63V
- Ultra-Small Package Sizes:
  - 1.6 mm x 1.2 mm
  - 2.0 mm x 1.6 mm
  - 2.5 mm x 2.0 mm
- High Frequency Stability: ±20 ppm, ±25 ppm, ±50 ppm
- Wide Temperature Range:
  - Automotive (Grade 1): –40°C to +125°C
  - Automotive (Grade 2): –40°C to +105°C
  - Automotive (Grade 3): –40°C to +85°C
- Excellent Shock and Vibration Immunity:
  - Shock: Qualified to MIL-STD-883E Method 2002.3, Test Condition G (30,000g)
  - Vibration: Qualified to MIL-STD-883E Method 2007.2, Test Condition C (70g)
- Spread Spectrum Clock Generation for EMI Reduction
- High Reliability
- Lead-Free and RoHS-Compliant

Applications

- Automotive Infotainment
- Automotive ADAS, Surround View Cameras
- In-Vehicle Networking, CAN bus, Ethernet

General Description

The DSA613 is a MEMS low power, ultra-small footprint, crystal-less family of clock generators. The DSA613 family is factory-configurable and generates up to three LVCMOS outputs from two PLLs. Each output can be configured to generate frequencies from 2 kHz to 100 MHz. The three-output DSA613 MEMS oscillators are excellent choices for use as clock references in automotive applications in which small size, low power consumption, and long-term reliability are paramount. The family of devices is AEC-Q100 qualified.

The DSA613 implements Microchip's proven PureSilicon™ MEMS technology to provide low jitter and high stability across a wide range of supply voltages and temperatures. By eliminating the external quartz crystal, Microchip's crystal-less™ clock generators significantly enhance reliability and accelerate product development.

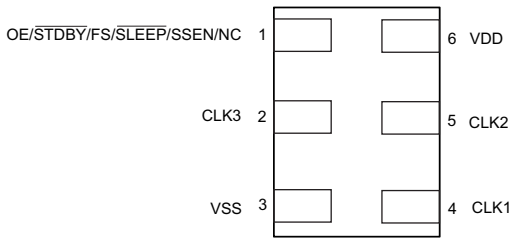
The DSA613 has one control input that can be configured to function as output enable/disable, standby, sleep, spread spectrum enable, and frequency select. The DSA613 is available in space saving 6-pin, 1.6 mm x 1.2 mm, 2.0 mm x 1.6 mm, and 2.5 mm x 2.0 mm VFLGA plastic packages.

The DSA613 spread spectrum function includes both center and down spreading for EMI reduction, and is explained further in the Spread Spectrum section.

The DSA613 is a highly configurable device and is factory programmed to meet the customer's needs. Microchip's ClockWorks Configurator must be used to choose the necessary options, create the final part number, data sheet, and order samples.

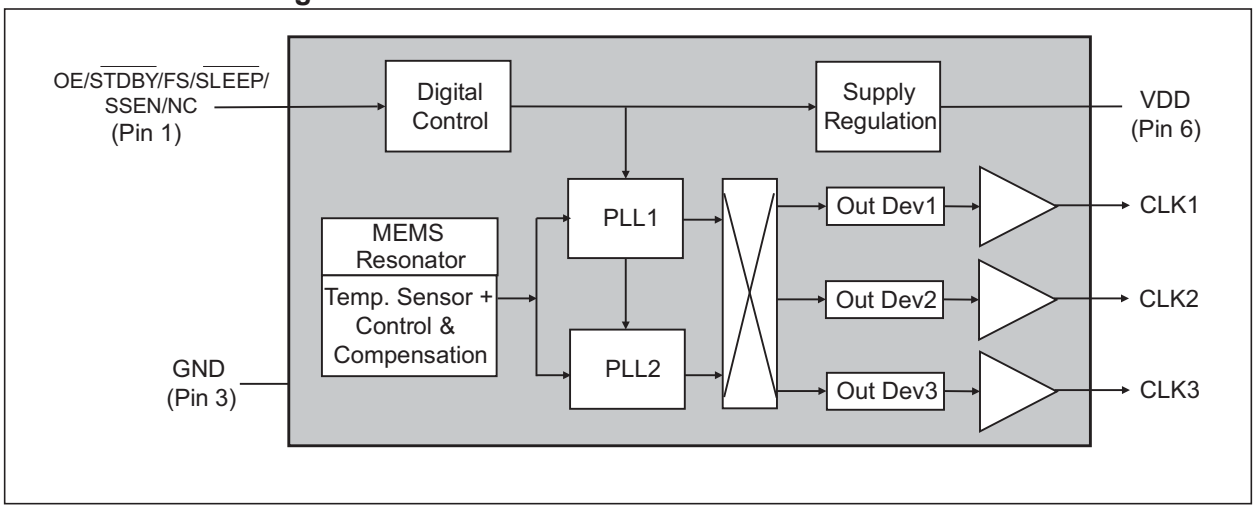
Package Type

DSA613
6-Lead VFLGA
(Top View)



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Functional Block Diagram



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1.0 ELECTRICAL CHARACTERISTICS

Absolute Maximum Ratings †

Supply Voltage ..... –0.3V to +4.0V
Input Voltage ..... –0.3V to V_{DD} + 0.3V
ESD Protection (HBM) ..... 4 kV
ESD Protection (MM) 400V
ESD Protection (CDM) ..... 2 kV

† Notice: Stresses above those listed under “Absolute Maximum Ratings” may cause permanent damage to the device. This is a stress rating only and functional operation of the device at those or any other conditions above those indicated in the operational sections of this specification is not intended. Exposure to maximum rating conditions for extended periods may affect device reliability.

ELECTRICAL CHARACTERISTICS

Electrical Characteristics: V_{DD} = 1.8V ±5% to 3.3V ±10%; T_A = –40°C to +125°C, unless noted.

Parameter	Symbol	Min.	Typ.	Max.	Units	Conditions
Supply Voltage	V_{DD}	1.71	—	3.63	V	Note 1
Active Supply Current	I_{DD}	—	5.2	6.5	mA	f_{CLK1} = 24 MHz, f_{CLK2} = 27 MHz, f_{CLK3} = 12 MHz, V_{DD} = 1.8V, No Load
Active Supply Current (Sleep Mode, 1 PLL Off)	I_{DDSL}	—	3	—	mA	CLK2 = SLEEP, f_{CLK1} = 25 MHz, V_{DD} = 1.8V, No Load
Active Supply Current (32.768 kHz Output Only)	I_{DD32k}	—	1.4	—	mA	f_{CLK3} = 32.768 kHz, V_{DD} = 1.8V, No Load
Standby Supply Current, Note 2	I_{STDBY}	—	1.0	—	µA	V_{DD} = 1.8V/2.5V
		—	1.5	—		V_{DD} = 3.3V
Frequency Stability, Note 3	Δf	—	—	±20	ppm	All temperature ranges
		—	—	±25		
		—	—	±50		
Aging	Δf	—	—	±5	ppm	1st year @ +25°C
		—	—	±1		Per year after the first year
Startup Time	t_{SU}	—	—	1.5	ms	From 90% V_{DD} to valid clock output, T = +25°C
Input Logic Levels, Note 4	V_{IH}	0.7 x V_{DD}	—	—	V	Input logic high
	V_{IL}	—	—	0.3 x V_{DD}		Input logic low
Output Disable Time	t_{DA}	—	—	200 + 2 Periods	ns	Note 5
Output Enable Time	t_{EN}	—	1.0	—	µs	Note 6
Enable Pull-Up Resistor	—	—	300	—	kΩ	If configured. Note 7
Output Logic Levels	V_{OHY}	0.8 x V_{DD}	—	—	V	I = 6 mA (high drive) or I = 3 mA (standard drive)
	V_{OLY}	—	—	0.2 x V_{DD}		I = –6 mA (high drive) or I = –3 mA (standard drive)
	V_{OHX}	0.8 x V_{DD}	—	—		I = 1 mA (low drive)
	V_{OLX}	—	—	0.2 x V_{DD}		I = –1 mA (low drive)

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ELECTRICAL CHARACTERISTICS (CONTINUED)

Electrical Characteristics: V_{DD} = 1.8V ±5% to 3.3V ±10%; T_A = –40°C to +125°C, unless noted.

Parameter	Symbol	Min.	Typ.	Max.	Units	Conditions
Output Transition Time, Rise Time/Fall Time	t_{RY1}/t_{FY1}	—	1.2	2.0	ns	V_{DD} = 1.8V, Standard drive 20% - 80% C_L = 10 pF (CLK1/CLK2)
		—	0.6	1.2		V_{DD} = 2.5V/3.3V, Standard drive 20% - 80% C_L = 10 pF (CLK1/CLK2)
	t_{RY2}/t_{FY2}	—	1.0	1.5		V_{DD} = 1.8V, High drive 20% - 80% C_L = 15 pF (CLK1/CLK2)
		—	0.5	1.0		V_{DD} = 2.5V/3.3V, High drive 20% - 80% C_L = 15 pF (CLK1/CLK2)
	t_{RX}/t_{FX}	—	2.5	3.5		V_{DD} = 1.8V, Low drive 20% - 80% C_L = 5 pF (CLK3)
		—	1.5	2.2		V_{DD} = 2.5V/3.3V, Low drive 20% - 80% C_L = 5 pF (CLK3)
Frequency	f0	0.002	—	100	MHz	Note 8
Output Duty Cycle	SYM	45	—	55	%	—
Period Jitter, RMS CLK1/CLK2	J_{PER}	—	20	—	ps	f_{CLK1} = 24 MHz, f_{CLK2} = 27 MHz, f_{CLK3} = 12 MHz, V_{DD} = 1.8V
		—	14	—		f_{CLK1} = 24 MHz, f_{CLK2} = 27 MHz, f_{CLK3} = 12 MHz, V_{DD} = 3.3V
		—	10	—		f_{CLK1} = 24 MHz, f_{CLK2} = 12 MHz, f_{CLK3} = 32.768 kHz, V_{DD} = 3.3V
Period Jitter, Peak-to-Peak CLK1/CLK2	J_{PER}	—	170	—	ps	f_{CLK1} = 24 MHz, f_{CLK2} = 27 MHz, f_{CLK3} = 12 MHz, V_{DD} = 1.8V
		—	140	—		f_{CLK1} = 24 MHz, f_{CLK2} = 27 MHz, f_{CLK3} = 12 MHz, V_{DD} = 3.3V
		—	80	—		f_{CLK1} = 24 MHz, f_{CLK2} = 12 MHz, f_{CLK3} = 32.768 kHz, V_{DD} = 3.3V
Cycle-to-Cycle Jitter, Peak CLK1/CLK2	J_{CY-CY}	—	150	—	ps	f_{CLK1} = 24 MHz, f_{CLK2} = 27 MHz, f_{CLK3} = 12 MHz, V_{DD} = 1.8V
		—	120	—		f_{CLK1} = 24 MHz, f_{CLK2} = 27 MHz, f_{CLK3} = 12 MHz, V_{DD} = 3.3V
		—	70	—		f_{CLK1} = 24 MHz, f_{CLK2} = 12 MHz, f_{CLK3} = 32.768 kHz, V_{DD} = 3.3V

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ELECTRICAL CHARACTERISTICS (CONTINUED)

Electrical Characteristics: V_{DD} = 1.8V ±5% to 3.3V ±10%; T_A = –40°C to +125°C, unless noted.

Parameter	Symbol	Min.	Typ.	Max.	Units	Conditions
Period Jitter, RMS CLK3	J_{PER}	—	40	—	ps	f_{CLK1} = 24 MHz, f_{CLK2} = 27 MHz, f_{CLK3} = 12 MHz, V_{DD} = 1.8V
		—	35	—		f_{CLK1} = 24 MHz, f_{CLK2} = 27 MHz, f_{CLK3} = 12 MHz, V_{DD} = 3.3V
Period Jitter, Peak-to-Peak CLK3	J_{PER}	—	270	—	ps	f_{CLK1} = 24 MHz, f_{CLK2} = 27 MHz, f_{CLK3} = 12 MHz, V_{DD} = 1.8V
		—	220	—		f_{CLK1} = 24 MHz, f_{CLK2} = 27 MHz, f_{CLK3} = 12 MHz, V_{DD} = 3.3V
Cycle-to-Cycle Jitter, Peak CLK3	J_{CY-CY}	—	235	—	ps	f_{CLK1} = 24 MHz, f_{CLK2} = 27 MHz, f_{CLK3} = 12 MHz, V_{DD} = 1.8V
		—	190	—		f_{CLK1} = 24 MHz, f_{CLK2} = 27 MHz, f_{CLK3} = 12 MHz, V_{DD} = 3.3V

Note 1: V_{DD} pin should be filtered with a 0.1 µF capacitor.

2: Excludes pull-up current.

3: Includes frequency variations due to initial tolerance, temperature, and power supply voltage.

4: Input waveform must be monotonic with rise/fall time < 10 ms.

5: Output disable time takes up to two Periods of the output waveform, plus 200 ns.

6: For parts configured with OE, not Standby.

7: Output is enabled if pad is floated or not connected.

8: CLK3 maximum frequency is 80 MHz.

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TEMPERATURE SPECIFICATIONS (Note 1)

Parameters	Symbol	Min.	Typ.	Max.	Units	Conditions
Temperature Ranges						
Junction Operating Temperature	T_J	—	—	+150	°C	—
Storage Temperature Range	T_S	–55	—	+150	°C	—
Lead Temperature	—	—	+260	—	°C	Soldering, 40s

Note 1: The maximum allowable power dissipation is a function of ambient temperature, the maximum allowable junction temperature and the thermal resistance from junction to air (i.e., T_A, T_J, θ_{JA}). Exceeding the maximum allowable power dissipation will cause the device operating junction temperature to exceed the maximum +150°C rating. Sustained junction temperatures above +150°C can impact the device reliability.

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2.0 PIN DESCRIPTIONS

The DSA613 is a highly configurable device and can be factory programmed in many different ways to meet the customer's needs. Microchip's ClockWorks Configurator http://clockworks.microchip.com/Timing/ must be used to choose the necessary options, create the final part number, data sheet, and order samples. The descriptions of the pins are listed in Table 2-1.

TABLE 2-1: DSA613 PIN FUNCTION TABLE

Pin Number	Pin Name	Description
1	OE	Output Enable: H = Active, L = Disabled (High Impedance).
	$\overline{\text{STDBY}}$	Standby: H = Device is active, L = Device is in standby (Low Power Mode).
	FS	Frequency Select: H = Output Frequency 1, L = Output Frequency 2.
	$\overline{\text{SLEEP}}$	Sleep: H= Output Enabled, L= Output and associated PLL Disabled.
	SSEN	Spread Spectrum: H = Enabled, L = Disabled.
2	CLK3	Factory configurable LVCMOS clock output 3: 2 kHz to 80 MHz, low drive.
3	VSS	Ground.
4	CLK1	Factory configurable LVCMOS clock output 1: 1 MHz to 100 MHz, standard drive or high drive.
5	CLK2	Factory configurable LVCMOS clock output 2: 1 MHz to 100 MHz, standard drive or high drive.
6	VDD	Power Supply: 1.71V to 3.63V.

An explanation of the different options listed in Table 2-1 follows.

2.1 Pin 1

This is a control pin and may be configured to fulfill one of six different functions. If not actively driven, a 10 kΩ pull-up resistor is recommended.

2.1.1 OUTPUT ENABLE (OE)

Pin 1 may be configured as OE. Any combination of outputs may be turned on and off according to the state of this pin (one, two, or all three outputs).

2.1.2 $\overline{\text{STANDBY}}$

Pin 1 may be configured as Standby. When the pin is low, all outputs will be off and the device will enter a low power mode.

2.1.3 $\overline{\text{SLEEP}}$

Pin 1 may be configured as Sleep. When the pin is low, one phase locked loop (PLL) will shut down, enabling power saving. Any outputs driven by that PLL will be turned off.

2.1.4 SPREAD SPECTRUM ENABLE (SSEN)

Pin 1 may be configured as Spread Spectrum Enable. When the pin is high, the associated output will be spread in frequency. When low, no spreading will occur.

2.1.5 FREQUENCY SELECT (FS)

Pin 1 may be configured as FS. Each output may be set to one of two pre-programmed frequencies (six pre-programmed frequencies in all).

2.1.6 NC

Pin 1 may be configured as NC. In this case, the pin is non-functional, and the device is programmed and fixed according to the choices in ClockWorks Configurator.

2.2 Pins 2 though 6

Pins 3 and 6 are the supply terminals, V_{SS} and V_{DD} respectively. Pins 2, 4, and 5 are the three clock outputs, CLK3, CLK1, and CLK2, respectively. CLK1 and CLK2 outputs are programmable to Standard and High Drive strengths settings. CLK3 is a fixed strength, low drive output. Visit ClockWorks Configurator to customize your device.

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3.0 SPREAD SPECTRUM

Spread spectrum is a slow modulation of the clock frequency over time. The PLL inside the MEMS oscillator is modulated with a triangular wave at 33 kHz. With such a slow modulation, the peak spectral energy of both the fundamental and all the harmonics is spread over a wider frequency range. This significantly reduces peak energy density, thus providing an EMI reduction.The triangular wave is chosen because of its flat spectral density.

The DSA613 MEMS oscillator family offers several modulation options: the spreading is either center spread or down spread with respect to the clock frequency. Center spreading ranges from ±0.25% to ±2.5%, while down spreading ranges from –0.25% to –3%.

If the clock frequency is 100 MHz and center spreading with ±1% is chosen, the output clock will range from 99 MHz to 101 MHz. If down spreading with –2% is chosen, the output clock will range from 98 MHz to 100 MHz.

Figure 3-1 and Figure 3-2 show a spectrum example of the DSA613 with a 33.333 MHz clock, modulated with central spread of ±1%.

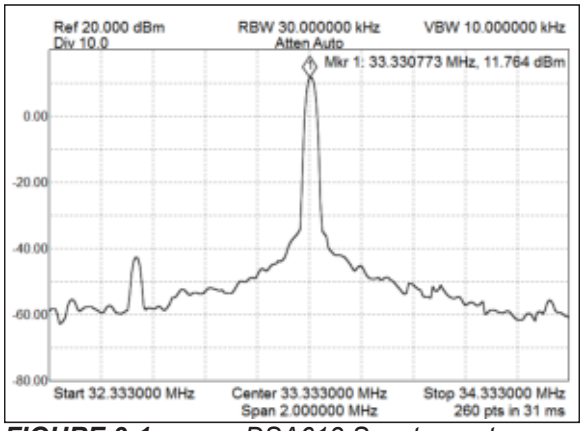


FIGURE 3-1: *DSA613 Spectrum at 33.333 MHz with Modulation Turned Off.*

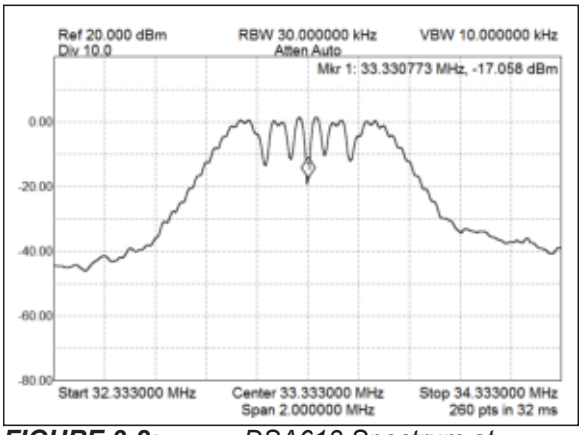


FIGURE 3-2: *DSA613 Spectrum at 33.333 MHz with Modulation Turned On.*

It is noticeable that the spread spectrum provides a reduction of about 10 dB from the peak power. Such a reduction may also be estimated by the following equation:

EQUATION 3-1:

$$EMI\ \text{Reduction} = 10 \times Log10(|S| \times fc \div RBW)$$

Where:

S	Peak-to-peak spread percentage (0.01, this example).
fc	Carrier frequency (33.333 MHz, this example).
RBW	Resolution bandwidth of the spectrum analyzer (30 kHz, this example).

The theoretical calculation for this example provides 10.45 dB, which is consistent with the measurement.

Similarly to the fundamental frequency, all the harmonics are spread and attenuated in similar fashion. Figure 3-3 shows how the DSA613 fundamental at 33.333 MHz and its odd harmonics are attenuated when various types of modulations are selected. For picture clarity, only the center spread options are shown. However, down spread with corresponding percentage provides the same level of harmonic attenuation (e.g. central spread of ±1% provides the same harmonics attenuation of down spread with –2%).

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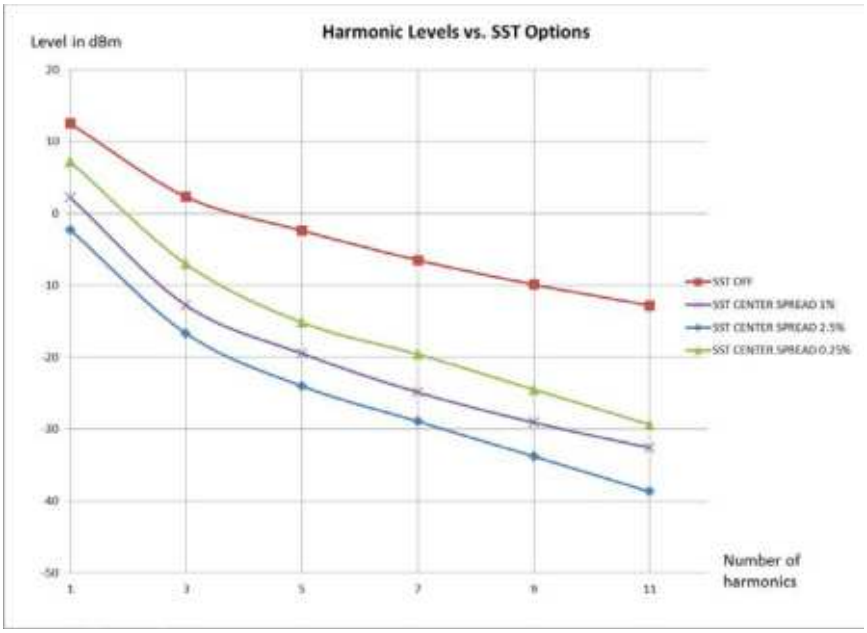


FIGURE 3-3: *DSA613 Harmonic Levels with Various Spread Spectrum Options.*

Visit Microchip's ClockWorks Configurator to select Spread Spectrum options.

4.0 OUTPUT WAVEFORM

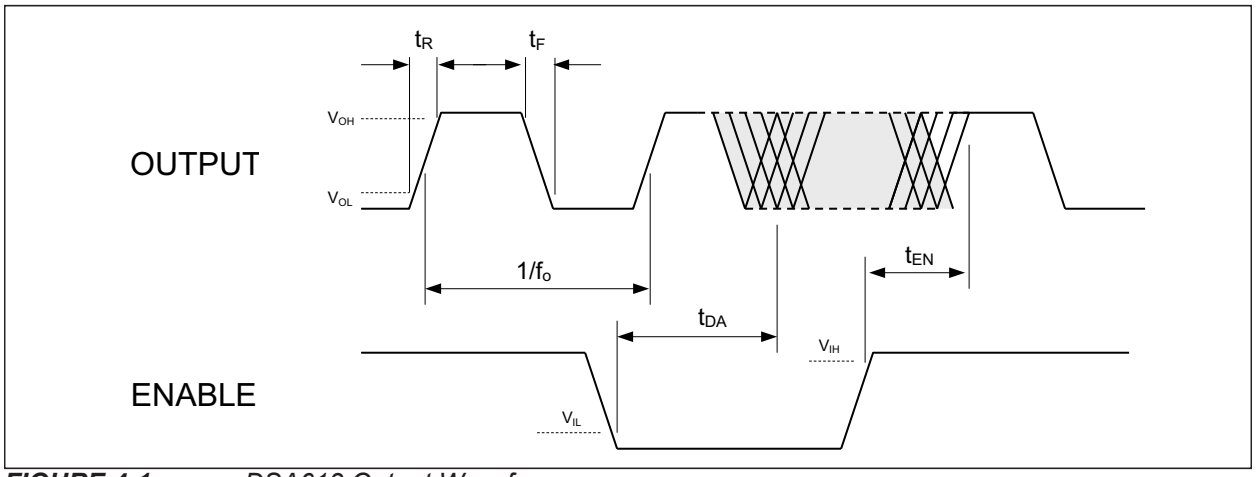


FIGURE 4-1: *DSA613 Output Waveform.*

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5.0 BOARD LAYOUT

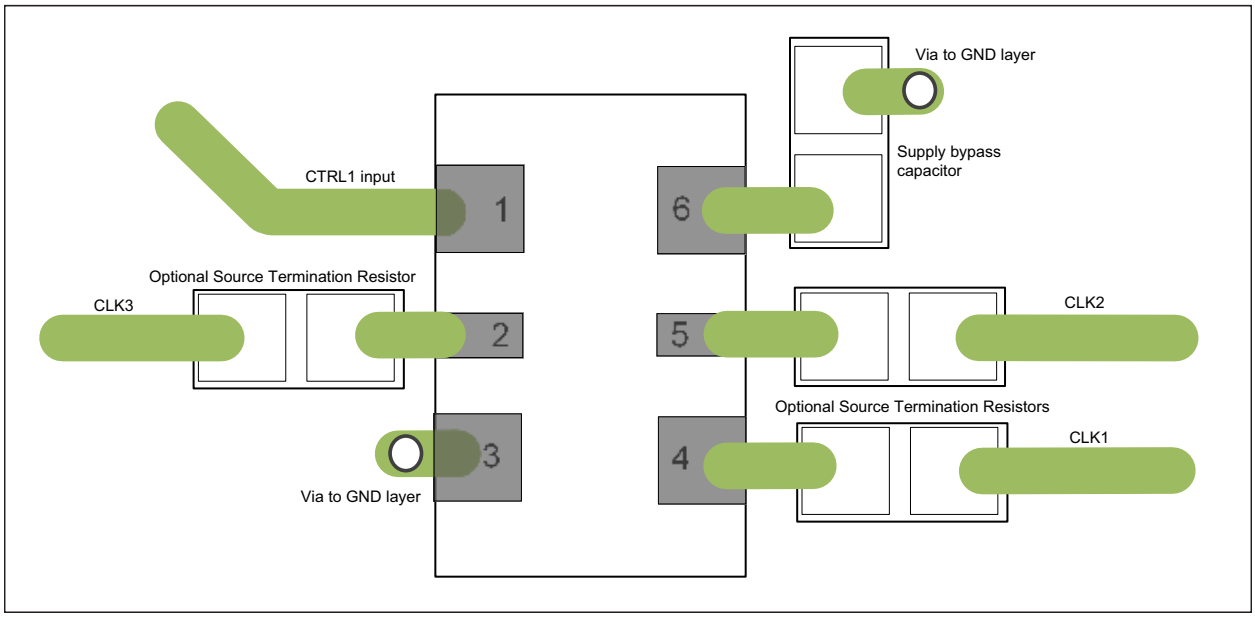


FIGURE 5-1: *DSA613 Board Layout.*

6.0 SOLDER REFLOW PROFILE

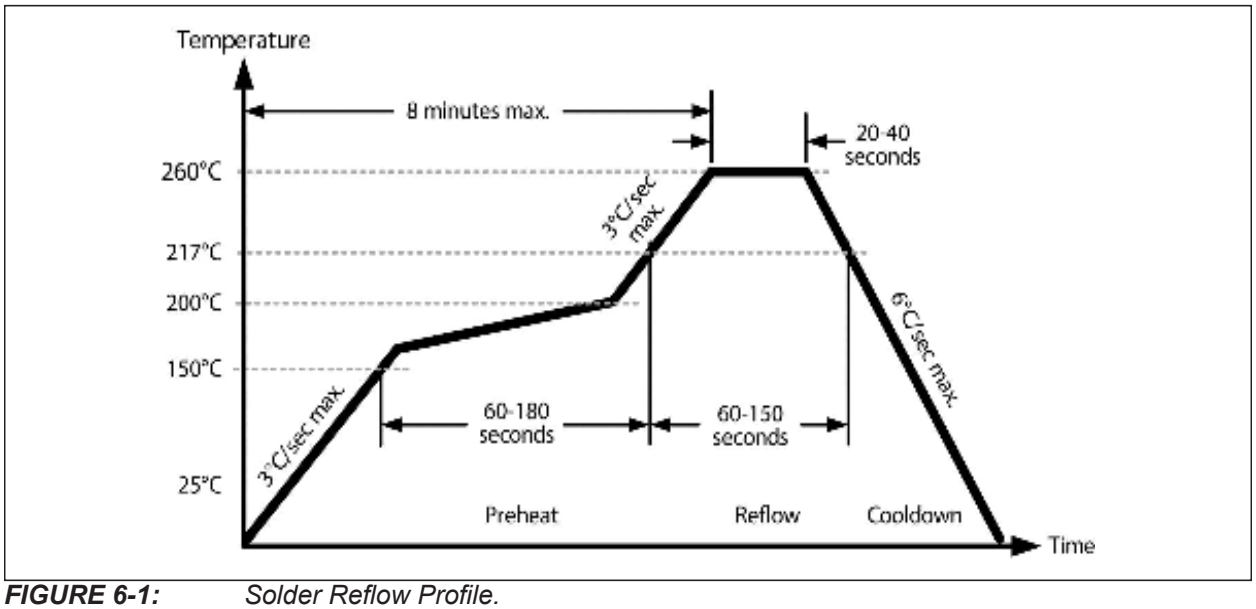


FIGURE 6-1: *Solder Reflow Profile.*

TABLE 6-1: SOLDER REFLOW

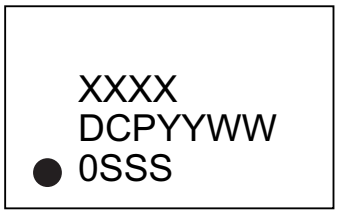
MSL 1 @ 260°C Refer to JSTD-020C	
Ramp-Up Rate (200°C to Peak Temp.)	3°C/sec. max.
Preheat Time 150°C to 200°C	60 to 180 sec.
Time Maintained above 217°C	60 to 150 sec.
Peak Temperature	255°C to 260°C
Time within 5°C of Actual Peak	20 to 40 sec.
Ramp-Down Rate	6°C/sec. max.
Time 25°C to Peak Temperature	8 minutes max.

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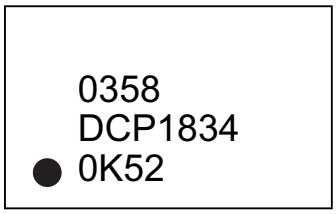
7.0 PACKAGING INFORMATION

7.1 Package Marking Information

6-Lead VFLGA*
(2.5mm x 2.0mm)



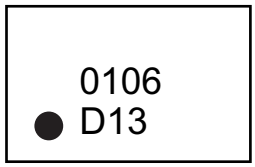
Example



6-Lead VFLGA*
(1.2mm x 1.6mm)
(1.6mm x 2.0mm)



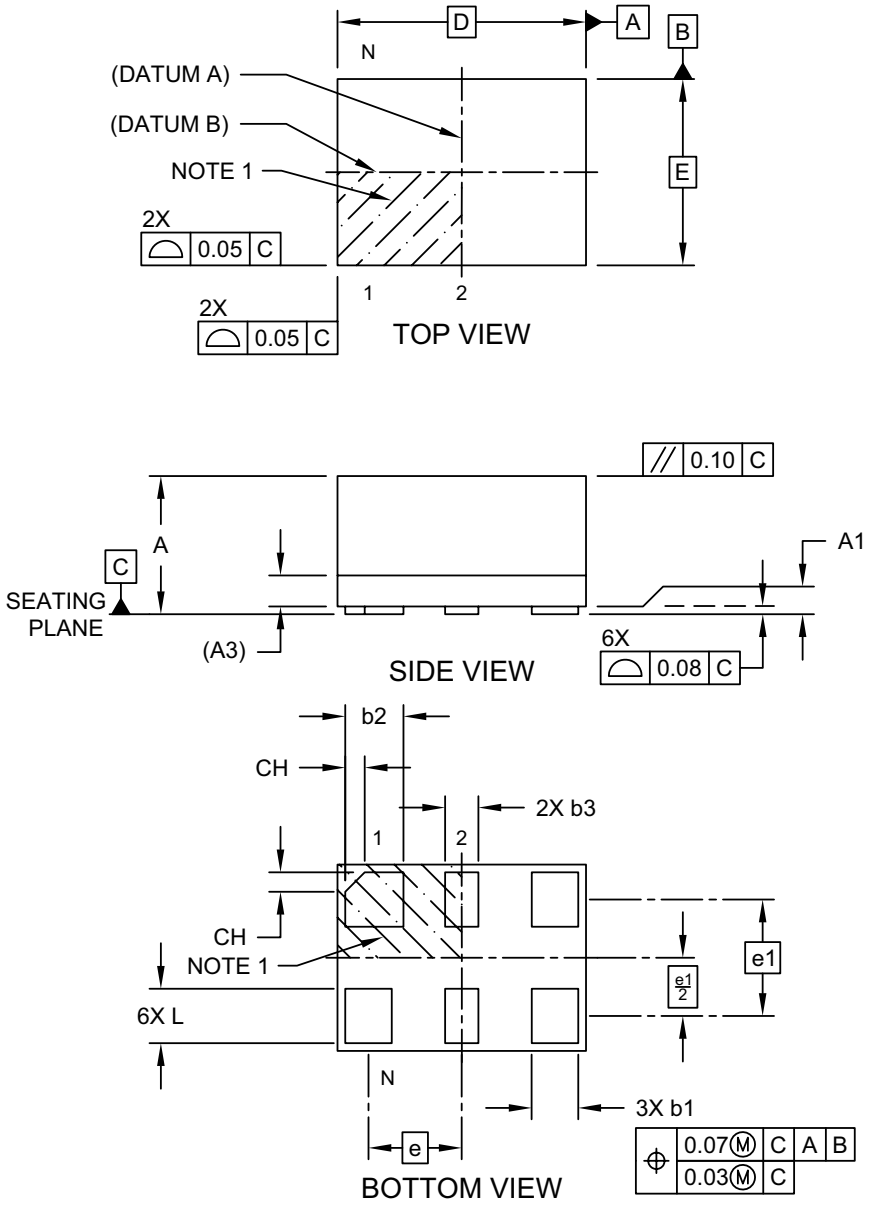
Example



Legend:	XX...X	Product code or customer-specific information
	Y	Year code (last digit of calendar year)
	YY	Year code (last 2 digits of calendar year)
	WW	Week code (week of January 1 is week ‘01’)
	NNN	Alphanumeric traceability code
	(e3)	Pb-free JEDEC® designator for Matte Tin (Sn)
	*	This package is Pb-free. The Pb-free JEDEC designator ((e3)) can be found on the outer packaging for this package.
	●, ▲, ▼	Pin one index is identified by a dot, delta up, or delta down (triangle mark).
Note:		In the event the full Microchip part number cannot be marked on one line, it will be carried over to the next line, thus limiting the number of available characters for customer-specific information. Package may or may not include the corporate logo.
		Underbar (_) and/or Overbar (¯) symbol may not be to scale.

6-Lead Very Thin Fine Pitch Land Grid Array (AVA) - 1.6x1.2 mm Body [VFLGA]

Note: For the most current package drawings, please see the Microchip Packaging Specification located at http://www.microchip.com/packaging

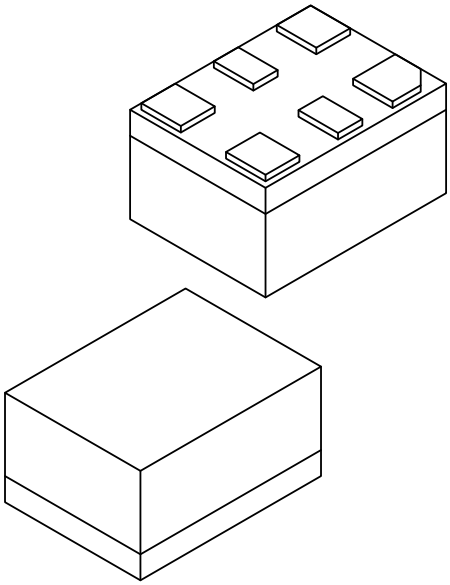


Microchip Technology Drawing C04-1203A Sheet 1 of 2

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6-Lead Very Thin Fine Pitch Land Grid Array (AVA) - 1.6x1.2 mm Body [VFLGA]

Note: For the most current package drawings, please see the Microchip Packaging Specification located at http://www.microchip.com/packaging



Units		MILLIMETERS		
Dimension Limits		MIN	NOM	MAX
Number of Terminals	N		6	
Terminal Pitch	e		0.60 BSC	
Terminal Pitch	e1		0.75 BSC	
Overall Height	A	0.79	0.84	0.89
Standoff	A1	0.00	0.02	0.05
Substrate Thickness (with Terminals)	A3		0.20 REF	
Overall Length	D		1.60 BSC	
Overall Width	E		1.20 BSC	
Terminal Width	b1	0.25	0.30	0.35
Terminal Width	b2	0.325	0.375	0.425
Terminal Width	b3	0.20	0.25	0.30
Terminal Length	L	0.30	0.35	0.40
Terminal 1 Index Chamfer	CH	-	0.125	-

Notes:

1. Pin 1 visual index feature may vary, but must be located within the hatched area.
2. Package is saw singulated
3. Dimensioning and tolerancing per ASME Y14.5M

BSC: Basic Dimension. Theoretically exact value shown without tolerances.

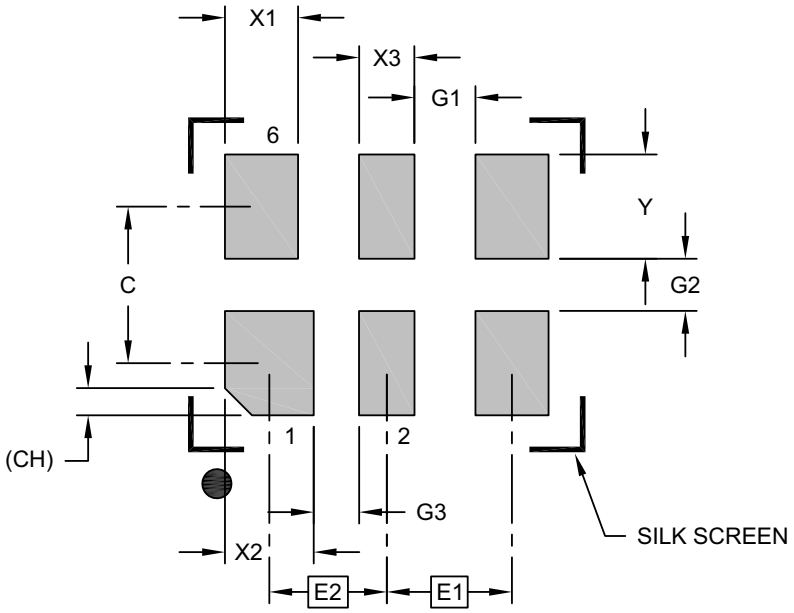
REF: Reference Dimension, usually without tolerance, for information purposes only.

Microchip Technology Drawing C04-1203A Sheet 2 of 2

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6-Lead Very Thin Fine Pitch Land Grid Array (AVA) - 1.6x1.2 mm Body [VFLGA]

Note: For the most current package drawings, please see the Microchip Packaging Specification located at http://www.microchip.com/packaging



RECOMMENDED LAND PATTERN

Units		MILLIMETERS		
Dimension Limits		MIN	NOM	MAX
Contact Pitch (X3)	E1		0.60 BSC	
Contact Pitch	E2		0.56 BSC	
Contact Spacing	C		0.75	
Contact Width (X3)	X1			0.35
Contact Width	X2			0.43
Contact Width (X2)	X3			0.27
Contact Pad Length (X6)	Y			0.50
Space Between Contacts (X4)	G1	0.29		
Space Between Contacts (X3)	G2	0.25		
Space Between Contacts	G3	0.22		
Contact 1 Index Chamfer	CH		0.13 X 45° REF	

Notes:

1. Dimensioning and tolerancing per ASME Y14.5M

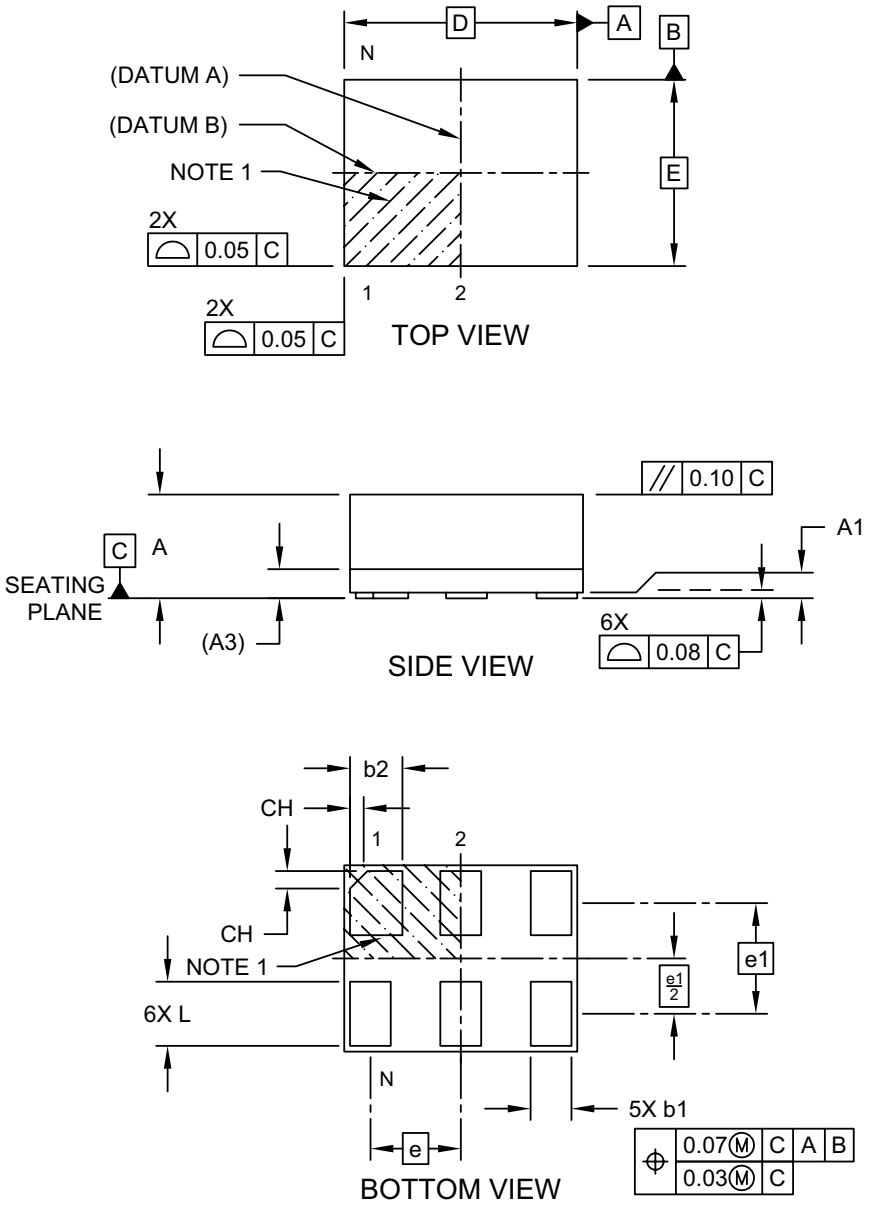
   BSC: Basic Dimension. Theoretically exact value shown without tolerances.

Microchip Technology Drawing C04-3203A

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6-Lead Very Thin Fine Pitch Land Grid Array (ATA) - 2.0x1.6 mm Body [VFLGA]

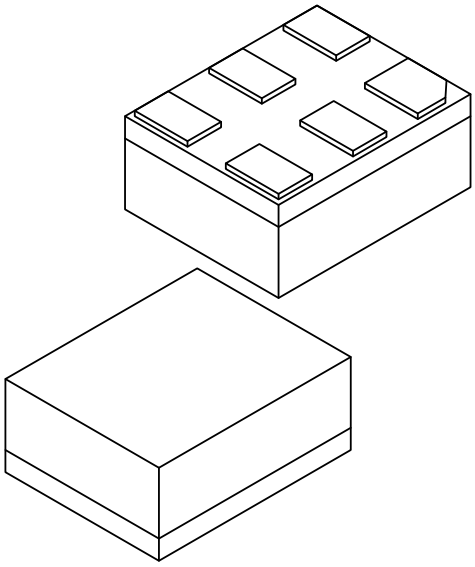
Note: For the most current package drawings, please see the Microchip Packaging Specification located at http://www.microchip.com/packaging



Microchip Technology Drawing C04-1201A Sheet 1 of 2

6-Lead Very Thin Fine Pitch Land Grid Array (ATA) - 2.0x1.6 mm Body [VFLGA]

Note: For the most current package drawings, please see the Microchip Packaging Specification located at http://www.microchip.com/packaging



Units		MILLIMETERS		
Dimension Limits		MIN	NOM	MAX
Number of Terminals	N		6	
Terminal Pitch	e		0.775 BSC	
Terminal Pitch	e1		0.95 BSC	
Overall Height	A	0.79	0.84	0.89
Standoff	A1	0.00	0.02	0.05
Substrate Thickness (with Terminals)	A3		0.20 REF	
Overall Length	D		2.00 BSC	
Overall Width	E		1.60 BSC	
Terminal Width	b1	0.30	0.35	0.40
Terminal Width	b2	0.40	0.45	0.50
Terminal Length	L	0.50	0.55	0.60
Terminal 1 Index Chamfer	CH	-	0.15	-

Notes:

1. Pin 1 visual index feature may vary, but must be located within the hatched area.
2. Package is saw singulated
3. Dimensioning and tolerancing per ASME Y14.5M

   BSC: Basic Dimension. Theoretically exact value shown without tolerances.

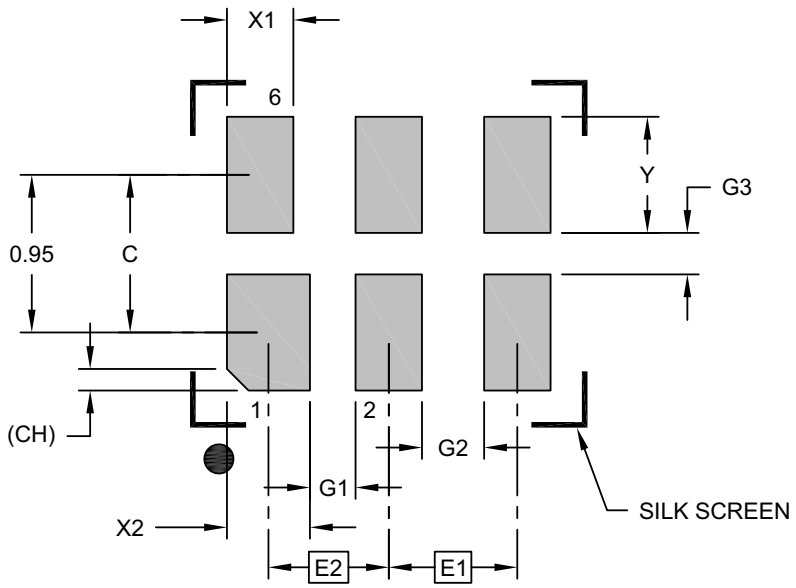
   REF: Reference Dimension, usually without tolerance, for information purposes only.

Microchip Technology Drawing C04-1201A Sheet 2 of 2

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6-Lead Very Thin Fine Pitch Land Grid Array (ATA) - 2.0x1.6 mm Body [VFLGA]

Note: For the most current package drawings, please see the Microchip Packaging Specification located at http://www.microchip.com/packaging



RECOMMENDED LAND PATTERN

Units		MILLIMETERS		
Dimension Limits		MIN	NOM	MAX
Contact Pitch	E1	0.78 BSC		
Contact Pitch	E2	0.73 BSC		
Contact Spacing	C		0.95	
Contact Width (X4)	X1			0.40
Contact Width (X2)	X2			0.45
Contact Pad Length (X6)	Y			0.70
Space Between Contacts (X4)	G1	0.28		
Space Between Contacts (X3)	G2	0.38		
Space Between Contacts (X3)	G3	0.25		
Contact 1 Index Chamfer	CH	0.13 X 45° REF		

Notes:

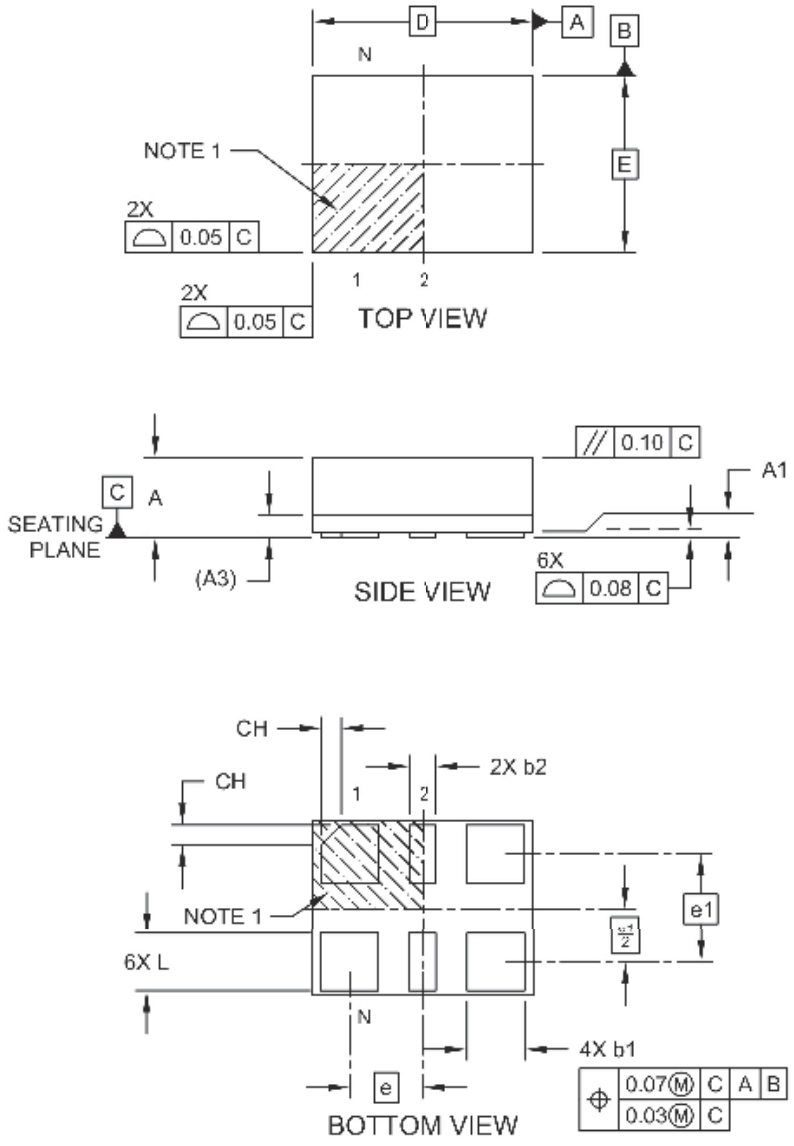
1. Dimensioning and tolerancing per ASME Y14.5M

   BSC: Basic Dimension. Theoretically exact value shown without tolerances.

Microchip Technology Drawing C04-3201A

6-Lead Very Thin Fine Pitch Land Grid Array (AWA) - 2.5x2.0 mm Body [VFLGA]

Note: For the most current package drawings, please see the Microchip Packaging Specification located at http://www.microchip.com/packaging

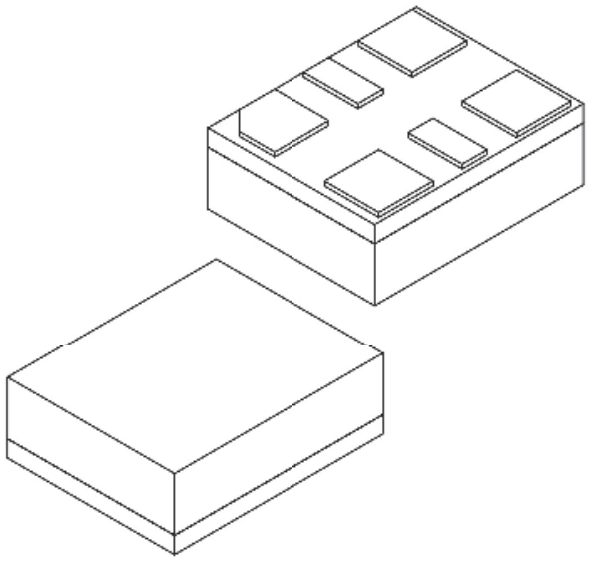


Microchip Technology Drawing C04-01204 Rev C Sheet 1 of 2

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6-Lead Very Thin Fine Pitch Land Grid Array (AWA) - 2.5x2.0 mm Body [VFLGA]

Note: For the most current package drawings, please see the Microchip Packaging Specification located at http://www.microchip.com/packaging



Units		MILLIMETERS		
Dimension Limits		MIN	NOM	MAX
Number of Terminals	N		6	
Terminal Pitch	e		0.825 BSC	
Terminal Pitch	e1		1.25 BSC	
Overall Height	A	0.79	0.84	0.89
Standoff	A1	0.00	0.02	0.05
Substrate Thickness (with Terminals)	A3		0.20 REF	
Overall Length	D		2.50 BSC	
Overall Width	E		2.00 BSC	
Terminal Width	b1	0.60	0.65	0.70
Terminal Width	b2	0.25	0.30	0.35
Terminal Length	L	0.60	0.65	0.70
Terminal 1 Index Chamfer	CH	-	0.225	-

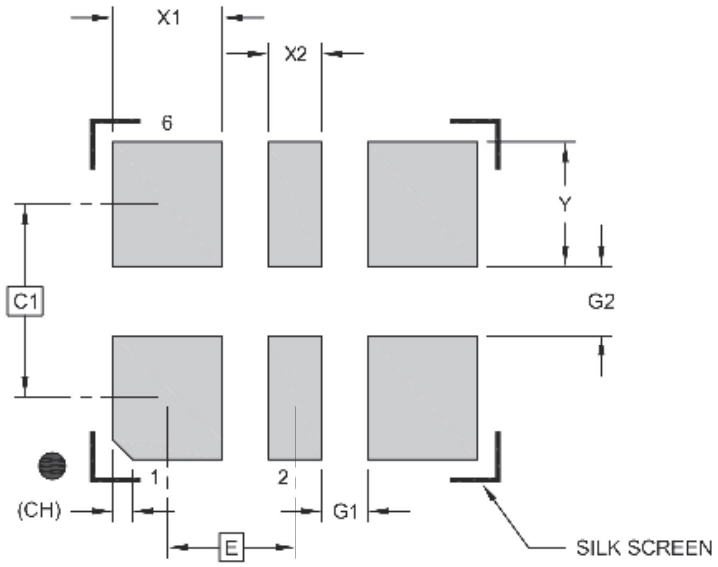
Notes:

1. Pin 1 visual index feature may vary, but must be located within the hatched area.
2. Dimensioning and tolerancing per ASME Y14.5M
   BSC: Basic Dimension. Theoretically exact value shown without tolerances.
   REF: Reference Dimension, usually without tolerance, for information purposes only.

Microchip Technology Drawing C04-01204 Rev C Sheet 2 of 2

6-Lead Very Thin Fine Pitch Land Grid Array (AWA) - 2.5x2.0 mm Body [VFLGA]

Note: For the most current package drawings, please see the Microchip Packaging Specification located at http://www.microchip.com/packaging



RECOMMENDED LAND PATTERN

Units		MILLIMETERS		
Dimension Limits		MIN	NOM	MAX
Contact Pitch	E	0.825 BSC		
Contact Spacing	C	1.25 BSC		
Contact Width (X4)	X1			0.70
Contact Width (X2)	X2			0.35
Contact Pad Length (X6)	Y			0.80
Space Between Contacts (X4)	G1	0.30		
Space Between Contacts (X3)	G2	0.45		
Contact 1 Index Chamfer	CH	0.13 X 45° REF		

Notes:

1. Dimensioning and tolerancing per ASME Y14.5M

BSC: Basic Dimension. Theoretically exact value shown without tolerances.

Microchip Technology Drawing C04-03204 Rev C

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APPENDIX A: REVISION HISTORY

Revision A (October 2019)

- Initial release of DSA613 as Microchip data sheet DS20006262A.

NOTES:

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PRODUCT IDENTIFICATION SYSTEM

To order or obtain information, e.g., on pricing or delivery, contact your local Microchip representative or sales office.

PART NO.	X	X	X	X	-XXXX	X	X
Device	Package	Temperature	Frequency Stability	Code Rev.	Configuration #	Special Processing	Automotive Suffix

Device:	DSA613:	Three-Output Low Power MEMS Clock Generator for Automotive	
Package:	R	=	6-Lead 2.5 mm x 2.0 mm VFLGA
	N	=	6-Lead 2.0 mm x 1.6 mm VFLGA
	P	=	6-Lead 1.6 mm x 1.2 mm VFLGA
Temperature:	A	=	–40°C to +125°C (Automotive Grade 1)
	L	=	–40°C to +105°C (Automotive Grade 2)
	I	=	–40°C to +85°C (Automotive Grade 3)
Frequency Stability:	1	=	±50 ppm
	2	=	±25 ppm
	3	=	±20 ppm
Code Revision:	A	=	1st Revision
Configuration Number:	User-Defined in the ClockWorks Configurator		
Special Processing:	<blank>=		140/Tube (R Package Option)
	<blank>=		100/Bag (N & P Package Options)
	T	=	1,000/Reel
	B	=	3,000/Reel
Automotive Suffix:	VXX = Automotive Suffix in which “XX” is assigned by Microchip.		

The DSA613 is a highly configurable device and is factory programmed to meet the customer’s needs. Microchip’s ClockWorks Configurator must be used to choose the necessary options, create the final part number, data sheet, and order samples.

Examples:

a) DSA613RI1A-0024TVA0:
Three-Output Low Power MEMS Clock Generator for Automotive, 6-Lead 2.5 mm x 2.0 mm VFLGA, –40°C to +85°C, ±50 ppm, 1st Revision, 1,000/Reel

b) DSA613NL2A-2885VA0:
Three-Output Low Power MEMS Clock Generator for Automotive, 6-Lead 2.0 mm x 1.6 mm VFLGA, –40°C to +105°C, ±25 ppm, 1st Revision, 100/Bag

c) DSA613PA3A-8751BVA0:
Three-Output Low Power MEMS Clock Generator for Automotive, 6-Lead 1.6 mm x 1.2 mm VFLGA, –40°C to +125°C, ±20 ppm, 1st Revision, 3,000/Reel

Note 1: Tape and Reel identifier only appears in the catalog part number description. This identifier is used for ordering purposes and is not printed on the device package. Check with your Microchip Sales Office for package availability with the Tape and Reel option.

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NOTES:

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Note the following details of the code protection feature on Microchip devices:

- Microchip products meet the specification contained in their particular Microchip Data Sheet.
- Microchip believes that its family of products is one of the most secure families of its kind on the market today, when used in the intended manner and under normal conditions.
- There are dishonest and possibly illegal methods used to breach the code protection feature. All of these methods, to our knowledge, require using the Microchip products in a manner outside the operating specifications contained in Microchip's Data Sheets. Most likely, the person doing so is engaged in theft of intellectual property.
- Microchip is willing to work with the customer who is concerned about the integrity of their code.
- Neither Microchip nor any other semiconductor manufacturer can guarantee the security of their code. Code protection does not mean that we are guaranteeing the product as "unbreakable."

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